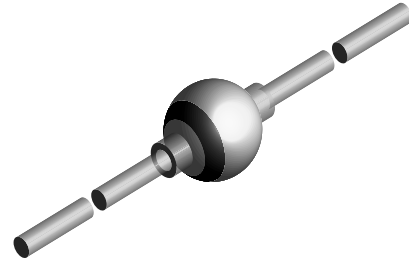


Standard Sinterglass Diode

Features

- High temperature metallurgically bonded constructed rectifiers
- Cavity-free glass passivated junction
- Hermetically sealed package
- 3.0 ampere operation at $T_{amb} = 70\text{ }^{\circ}\text{C}$ with no thermal runaway



17132

Mechanical Data

Case: Sintered glass case, G3

Terminals: Solder plated axial leads, solderable per MIL-STD-750, Method 2026

Mounting Position: Any

Weight: 1100 mg

Polarity: Color band denotes cathode end

Parts Table

Part	Type differentiation	Package
G3A	$V_{RRM} = 50\text{ V}$	G3
G3B	$V_{RRM} = 100\text{ V}$	G3
G3D	$V_{RRM} = 200\text{ V}$	G3
G3G	$V_{RRM} = 400\text{ V}$	G3
G3J	$V_{RRM} = 600\text{ V}$	G3
G3K	$V_{RRM} = 800\text{ V}$	G3
G3M	$V_{RRM} = 1000\text{ V}$	G3

Absolute Maximum Ratings

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Part	Symbol	Value	Unit
Reverse voltage = Repetitive peak reverse voltage	see electrical characteristics	G3A	$V_R = V_{RRM}$	50	V
	see electrical characteristics	G3B	$V_R = V_{RRM}$	100	V
	see electrical characteristics	G3D	$V_R = V_{RRM}$	200	V
	see electrical characteristics	G3G	$V_R = V_{RRM}$	400	V
	see electrical characteristics	G3J	$V_R = V_{RRM}$	600	V
	see electrical characteristics	G3K	$V_R = V_{RRM}$	800	V
	see electrical characteristics	G3M	$V_R = V_{RRM}$	1000	V
Maximum average forward rectified current	0.375 " (9.5 mm) lead length at $T_{amb} = 70\text{ }^{\circ}\text{C}$		$I_{F(AV)}$	3.0	A
Peak forward surge current	8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)		I_{FSM}	125	A
Maximum full load reverse current	full cycle average 0.375 " (9.5 mm) lead length at $T_{amb} = 70\text{ }^{\circ}\text{C}$		$I_{R(AV)}$	200	μA
Operating junction and storage temperature range			T_J, T_{STG}	-55 to +175	$^{\circ}\text{C}$

Maximum Thermal Resistance

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Typical thermal resistance ¹⁾	$R_{\theta JA}$	20	K/W
	$R_{\theta JL}$	10	K/W

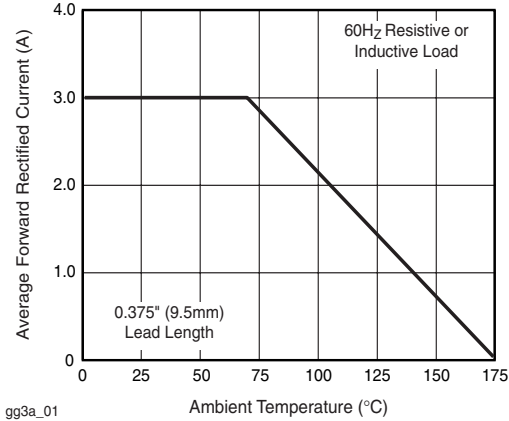
¹⁾ Thermal resistance from junction to ambient and from junction to lead at 0.375 " (9.5 mm) lead length, with both leads mounted between heatsinks

Electrical Characteristics

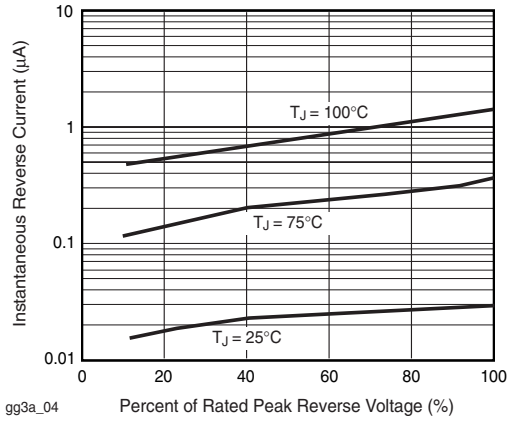
$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Part	Symbol	Typ.	Max	Unit
Maximum instantaneous forward voltage	$I_F = 3\text{ A}$	G3A	V_F		1.2	V
	$I_F = 3\text{ A}$	G3B	V_F		1.2	V
	$I_F = 3\text{ A}$	G3D	V_F		1.1	V
	$I_F = 3\text{ A}$	G3G	V_F		1.1	V
	$I_F = 3\text{ A}$	G3J	V_F		1.1	V
	$I_F = 3\text{ A}$	G3K	V_F		1.1	V
	$I_F = 3\text{ A}$	G3M	V_F		1.1	V
Maximum reverse current	$V_R = V_{RRM}, T_{amb} = 25\text{ }^{\circ}\text{C}$		I_R		5.0	μA
	$V_R = V_{RRM}, T_{amb} = 150\text{ }^{\circ}\text{C}$		I_R		100	μA
Typical reverse recovery time	$I_F = 0.5\text{ A}, I_R = 1.0\text{ A}, I_{rr} = 0.25\text{ A}$		t_{rr}	3.0		μs
Typical junction capacitance	$V_R = 4.0\text{ V}, f = 1\text{ MHz}$		C_J	40		pF

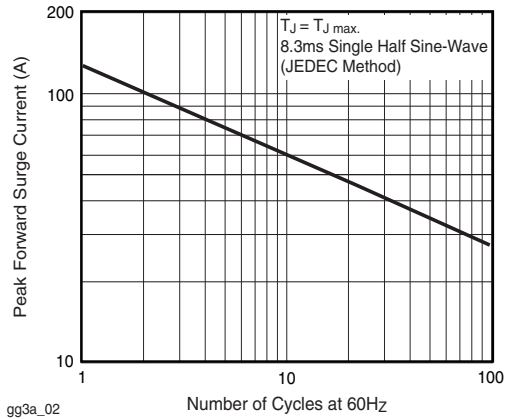
Typical Characteristics ($T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)



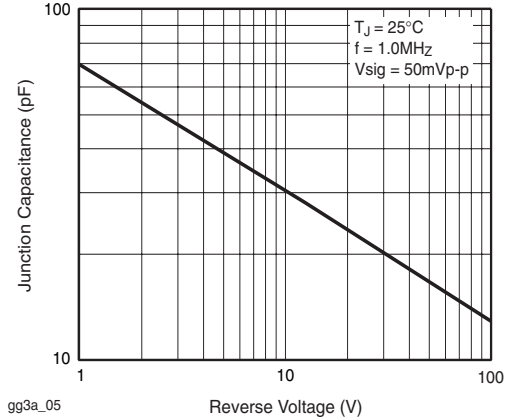
gg3a_01
Figure 1. Forward Current Derating Curve



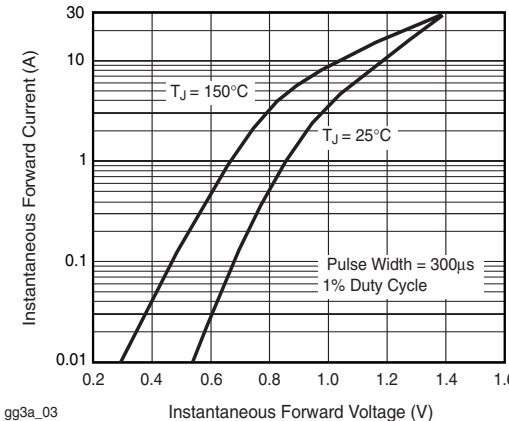
gg3a_04
Figure 4. Typical Reverse Characteristics



gg3a_02
Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

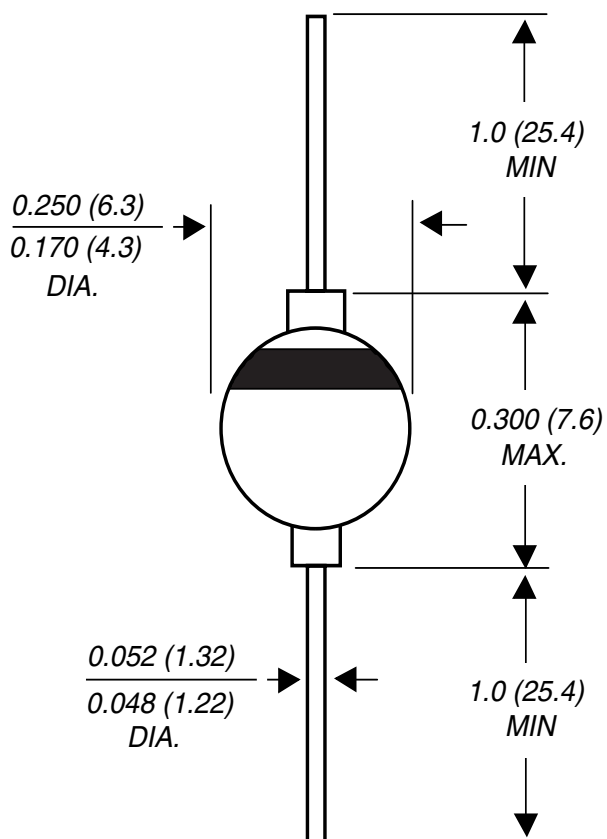


gg3a_05
Figure 5. Typical Junction Capacitance



gg3a_03
Figure 3. Typical Instantaneous Forward Characteristics

Package Dimensions in Inches (mm)



17169



Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design
and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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